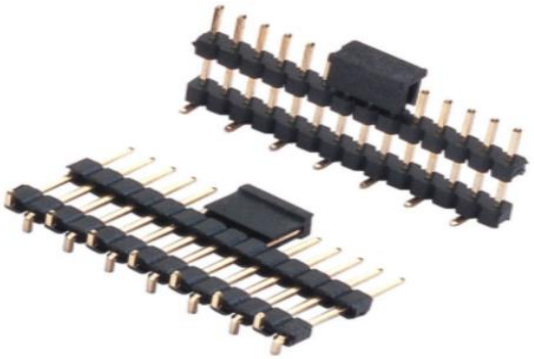
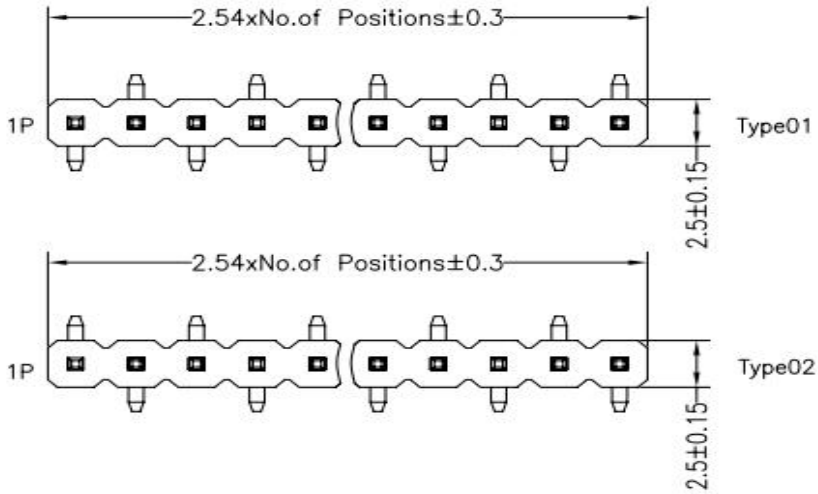
HECON
东莞市禾康电子有限公司
DONGGUAN HECON ELECTRONICS CO.,LTD

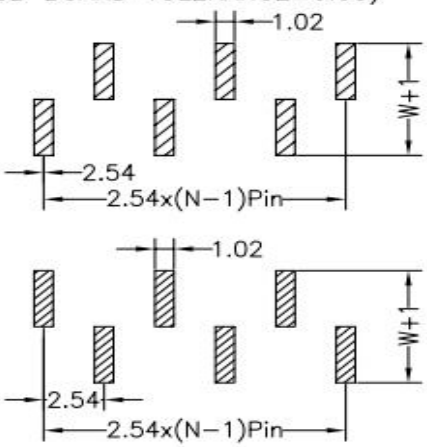
SPECIFICATIONS:

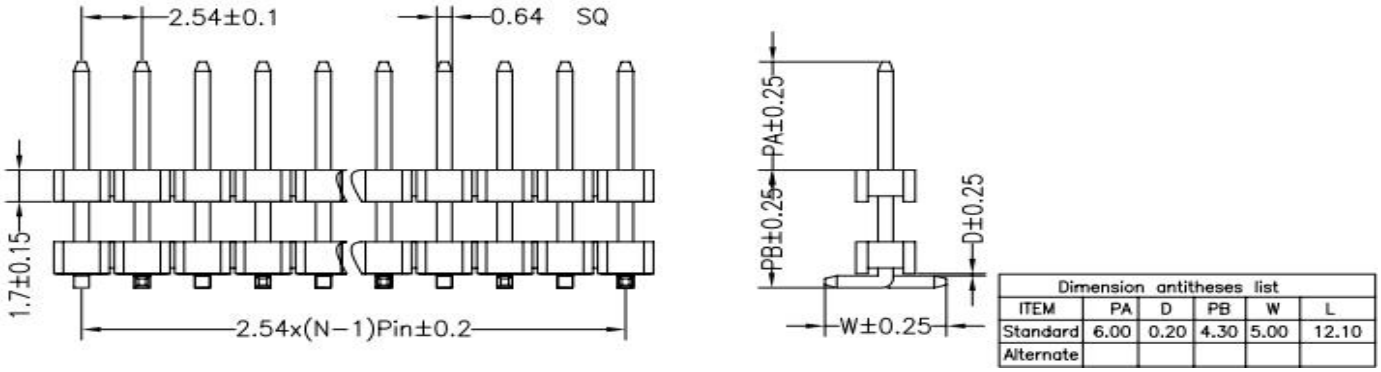
Rated Current	3.0AMP
Contact Resistance	20mΩ Max
Withstand Voltage	1000V AC/DC
Insulation Resistance	1000mΩ Min
Operation Temperature	- 40℃ to +105℃
Contact Material	Brass
Contact Plating	Au over Ni
Insulator Material	PA6T
Max. Processing Temp:	230℃ for 30-60 seconds
	260℃ for 10 seconds





Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)





Dimension antitheses list					
ITEM	PA	D	PB	W	L
Standard	6.00	0.20	4.30	5.00	12.10
Alternate					

Ordering Information

HC Series	No. of Pin Per Row	Insulator Option	N	Plating	Type	PIN Length	Packing	End code
HC-PH41721	2x01P	A=PBT		G0=Gold Flash	M=SMT	L=XXX	0=PE Bag	X
2.54mm Pin Header	2x40P	B=PA66		SN=Tin Plated		Confirm you need size of PA/PB/D/W	A=Tray	
		C=PA6T		SM=Matted Tin			T=Tube	
		D=PA46		S0=Gold/Tin			P=Tube+Cap	
		E=PA9T		G1=3u Gold			R=Reel+Cap	
		F=LCP		G2=5u Gold			M=Reel+Mylar	
		X=Special		G3=10u Gold			X=Special	
				G4=15u Gold				
				G5=30u Gold				
				S1=3u Gold/Tin				